

Title (en)  
METHOD FOR PRODUCING A METAL-CERAMIC SUBSTRATE, AND METAL-CERAMIC SUBSTRATE PRODUCED USING A METHOD OF THIS TYPE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES METALL-KERAMIK-SUBSTRATS UND METALL-KERAMIK-SUBSTRAT HERGESTELLT MIT EINEM SOLCHEN VERFAHREN

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN SUBSTRAT MÉTAL-CÉRAMIQUE ET SUBSTRAT MÉTAL-CÉRAMIQUE FABRIQUÉ AU MOYEN D'UN TEL PROCÉDÉ

Publication  
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Application  
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Abstract (en)  
[origin: WO2022200406A1] The present invention relates to a method for producing a metal-ceramic substrate (1) comprising: - providing a ceramic element (30) and at least one metal layer (10), wherein the ceramic element (30) and the at least one metal layer (10) extend along a main extension plane (HSE), - joining the ceramic element (30) to the at least one metal layer (10) to form a metal-ceramic substrate (1), in particular by means of a direct metal joining method, a hot isostatic pressing method and/or a soldering method. A structuring, preferably for forming an insulation of metal sections (10') and/or a recess, preferably for forming a solder stop is provided in the at least one metal layer (10) by means of a laser method and a chemical method, in particular an etching.

IPC 8 full level  
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